

ENERGY OF ADHESIVE BONDS
IN A COPPER–SOLID SYSTEM

*V.M. Juzevych, P.M. Soprunjuk, B.P. Coman¹,
P.V. Lugovyj*

G. Karpenko Physicomechanical Institute,
Nat. Acad. Sci. of Ukraine
(5, *Naukova Str.*, *L'viv 79601, Ukraine*;
e-mail: dep26@ah.ipm.lviv.ua),
¹Ivan Franko L'viv National University
(50, *Dragomanov Str.*, *L'viv 79005, Ukraine*)

S u m m a r y

Making use of the macroscopic methods of surface physics, the energy of adhesive bonds in nanosize layers near the interfaces between copper and various materials in a solid state (zinc, silicon, and quartz) has been considered. The energy of adhesive bonds and the adhesion work have been found to be of the order of magnitude as large as the interphase energy and the interphase tension, respectively. The behavior of temperature variations of the energy-related interphase and adhesive parameters of the Cu–Zn system has been studied.